



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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EXCEPTIONALLY SOFT, HIGHLY COMPLIANT GAP FILLER

Tflex[™] 600 is an exceptionally soft, highly compliant gap filling interface pad with a thermal conductivity of 3 W/mK. These outstanding properties are the result of a proprietary boron nitride filler in the composition.

The high conductivity, in combination with extreme softness produces incredibly low thermal resistances.

Tflex[™] 600 is naturally tacky and requires no additional adhesive coating that can inhibit thermal performance. Tflex[™] 600 is electrically insulating, stable from -45°C to 200°C and meets UL 94 V0 rating.

FEATURES AND BENEFITS

- Very high compliancy for low stress applications
- 3 W/mK thermal conductivity
- Available in thicknesses from 0.020" - 0.200" (0.5mm - 5.0mm)
- Naturally tacky, needs no further adhesive coating

APPLICATIONS

- Cooling components to the chassis or frame
- High speed mass storage drives
- RDRAM memory modules
- Heat pipe thermal solutions
- Automotive engine control units
- Telecommunications hardware

Tflex™ 600 Series Thermal Gap Filler

	Tflex™ 600	TEST METHOD
Construction & Composition	Boron nitride filled silicone elastomer	
Color	Blue-Violet	Visual
Thickness Range	0.020" (0.50mm) - 0.200" (5.08mm)	
Thickness Tolerance	± 10%	
Density (g/cc)	1.34	Helium Pycnometer
Hardness (Shore 00)	51; 3 seconds 48; 30 seconds	ASTM D2240
Tensile Strength	15 psi	ASTM D412
% Elongation	75	ASTM D412
Outgassing Conditions	Post cured	
Outgassing TML (weight %)	0.13%	ASTM E595
Outgassing CVCM (weight %)	0.05%	ASTM E595
UL Flammability Rating	94 V0	UL FILE E180840
Temperature Range	-45°C to 200°C	
Thermal Conductivity	3.0 W/mK	Hot Disk
Thermal Impedance @ 40 mils, 10 psi @ 1 mm, 69kPa	0.62°C-in ² /W 4.00°C-cm ² /W	ASTM D5470 (modified)
Thermal Expansion	430 ppm/°C	IPC-TM-650 2.4.24
Volume Resistivity	2 x 10 ¹³ ohm-cm	ASTM D257
Dielectric Constant @ 1MHz	331%	ASTM D150

STANDARD THICKNESSES

0.020 to 0.200-inch (0.5 to 5.0mm)

0.020 to 0.200-inch thick material available in 0.010-inch (0.25mm) increments

Inquire about availability of material and options above 0.200-inches

STANDARD SHEET SIZES

9 x 9" (229 x 229mm). 18 x 18" (457 x 457mm). 9 x 9" only over 0.100" thickness. Tflex™ 600 can be die cut to individual shapes. Pressure sensitive adhesive is not applicable for Tflex™ 600 products.

TACKY ONE SIDE ONLY

Tflex™ 600 is naturally tacky on both sides. Tflex™ 600 can be provided tacky on one side only. This is indicated by the suffix "DC1". This option offers good separation properties allowing the tacky side to stick to the heatsink/chassis/cold plate/etc. and the other "dry" side to release easily from the component(s).

REINFORCEMENT

Fiberglass is required in 0.020" (0.51mm) and 0.030" (0.76mm). Thicknesses of 0.040" (1.02mm) and above do not require reinforcement. Data for design engineer guidance only. Observed performance varies in application. Engineers are reminded to test the material in application.

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